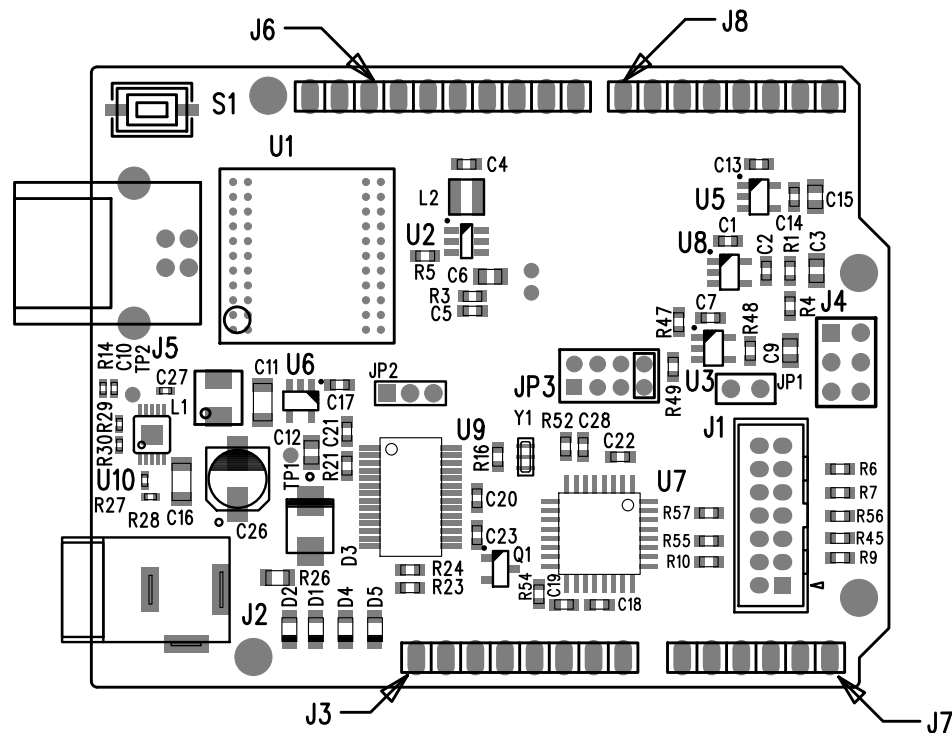



REVISION HISTORY				
ECO	REV	DESCRIPTION	APPR	DATE
—	1	PRODUCTION	MARK THOREN	03-25-15



## NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE REFLOW SOLDER BOTH SIDES. MAXIMUM SOLDER TEMPERATURE SHALL BE <250 DEGREES CELSIUS.
3. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON ALL BOARD EDGES.
4. DO NOT APPLY ANY ASSEMBLY OR QA STAMPS TO BOARD.
5. J1 THOUGH J8 AND JP3 ARE ALL MOUNTED ON THE TOP SIDE.
6. INSTALL SHUNT IN JP3 AS DEPICTED.
7. INSTALL STICK-ON BUMPONS, MP1-MP4, ON BOTTOM SIDE. (REFER TO SHEET 2, BOTTOM SIDE ASS'Y DRAWING).

APPROVALS		 <div> 1630 MCCARTHY BLVD  MILPITAS, CA 95035  PH: (408)432-1900  www.linear.com  LTC CONFIDENTIAL-  FOR CUSTOMER USE ONLY </div>	
PCB DES.	M. HAWKINS		
APP ENG.	MARK THOREN	TITLE: ASSEMBLY DRAWING, TOP LINDUINO ONE: LINEAR TECHNOLOGY ISOLATED ARDUINO-COMPATIBLE DEMONSTRATION BOARD	
		SIZE N/A	IC NO. LTM2884CY DEMO CIRCUIT 2026C
SCALE = NONE		REV. 1	
FILENAME: DC2026C-1.PCB		SHT 1 OF 2	